

1 ABSTRACT OF THE DISCLOSURE

2 The invention encompasses a board-on-chip package comprising an
3 insulative substrate having circuitry thereon and an opening therethrough.
4 A semiconductive-material-comprising die is adhered to the substrate and
5 electrically connected to the circuitry with a plurality of electrical
6 interconnects extending through the opening. A metal foil is in physical
7 contact with at least a portion of the die. The invention also
8 encompasses a method of forming a plurality of board-on-chip packages.
9 An insulative substrate is provided. Such substrate has a repeating
10 circuitry pattern thereon, and a plurality of openings therethrough. The
11 openings are in a one-to-one correspondence with individual of the
12 repeated circuitry patterns. A plurality of semiconductive-material-
13 comprising dies are adhered to the substrate. Circuitry supported by the
14 dies is electrically connected with the circuitry on the substrate utilizing
15 a plurality of electrical interconnects extending through the openings.
16 A metal foil is joined to the substrate and extended over the plurality
17 of dies. The substrate and metal foil are cut to form singulated die
18 packages comprising a single die, a portion of the substrate having a
19 single repeated pattern of the circuitry, and a portion of the metal foil.

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